

and (a)(2)(B)(II.B.) (shift in production to a foreign country) have not been met. None.

- TA-W-62,853; Irving Forest Products, Nashville Plantation, ME.
- TA-W-62,860; Ullman, A Division of American Greetings Corporation, Burgaw, NC.
- TA-W-62,926; SDS Lumber Company, Lumber Division, Bingen, WA.
- TA-W-62,968; The Longaberger Company, Global Procurement, Newark, OH.
- TA-W-62,968A; The Longaberger Company, Basket Department, Frazeyburg, OH.
- TA-W-63,158; Silver City Lumber, Inc., Three Forks, MT.
- TA-W-63,190; Bay Valley Foods, LLC, Portland, OR.
- TA-W-63,235; Southprint, Inc., Reidsville Division, Reidsville, NC.

The workers' firm does not produce an article as required for certification under Section 222 of the Trade Act of 1974.

- TA-W-63,197; Dan River, Inc., Danville Operations, Danville, VA.
- TA-W-63,226; Semperian, LLC, Div. of GMAC, LLC, Eugene, OR.
- TA-W-63,286; Brunswick Bowling and Billiards, Muskegon, MI.
- TA-W-63,297; Snider Transportation Services, Tyler, TX.
- TA-W-63,422; Springs Global U.S., Inc., Springs Direct Div., Springmaid Wamsutta Factory Store, Lancaster, SC.

The investigation revealed that criteria of Section 222(b)(2) has not been met. The workers' firm (or subdivision) is not a supplier to or a downstream producer for a firm whose workers were certified eligible to apply for TAA.

TA-W-63,241; Kataddin Precision Components, LLC, Bangor, ME.

I hereby certify that the aforementioned determinations were issued during the period of May 27 through May 30, 2008. Copies of these determinations are available for inspection in Room C-5311, U.S. Department of Labor, 200 Constitution Avenue, NW., Washington, DC 20210 during normal business hours or will be mailed to persons who write to the above address.

Dated: June 9, 2008.

Linda G. Poole,

Certifying Officer, Division of Trade Adjustment Assistance.

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DEPARTMENT OF LABOR

Employment and Training Administration

Investigations Regarding Certifications of Eligibility To Apply for Worker Adjustment Assistance and Alternative Trade Adjustment Assistance

Petitions have been filed with the Secretary of Labor under Section 221 (a) of the Trade Act of 1974 ("the Act") and are identified in the Appendix to this notice. Upon receipt of these petitions, the Director of the Division of Trade

Adjustment Assistance, Employment and Training Administration, has instituted investigations pursuant to Section 221 (a) of the Act.

The purpose of each of the investigations is to determine whether the workers are eligible to apply for adjustment assistance under Title II, Chapter 2, of the Act. The investigations will further relate, as appropriate, to the determination of the date on which total or partial separations began or threatened to begin and the subdivision of the firm involved.

The petitioners or any other persons showing a substantial interest in the subject matter of the investigations may request a public hearing, provided such request is filed in writing with the Director, Division of Trade Adjustment Assistance, at the address shown below, not later than June 26, 2008.

Interested persons are invited to submit written comments regarding the subject matter of the investigations to the Director, Division of Trade Adjustment Assistance, at the address shown below, not later than June 26, 2008.

The petitions filed in this case are available for inspection at the Office of the Director, Division of Trade Adjustment Assistance, Employment and Training Administration, U.S. Department of Labor, Room C-5311, 200 Constitution Avenue, NW., Washington, DC 20210.

Signed at Washington, DC, this 5th day of June 2008.

Elliott S. Kushner,

Certifying Officer, Division of Trade Adjustment Assistance.

APPENDIX

[TAA petitions instituted between 5/27/08 and 5/30/08]

TA-W	Subject firm (petitioners)	Location	Date of institution	Date of petition
63432	Kongsberg Driveline Systems (Wkrs)	Van Wert, OH	05/27/08	05/08/08
63433	General Motors Metal Fabricating Division (Wkrs)	Parma, OH	05/27/08	05/20/08
63434	Plastech Engineered Products (Comp)	Byesville, OH	05/27/08	05/23/08
63435	Gold Shield (Fleetwood) (Wkrs)	Riverside, CA	05/27/08	05/05/08
63436	Ponderay Newsprint Company (Wkrs)	Usk, WA	05/28/08	05/20/08
63437	Tytex, Inc. (Comp)	Woonsocket, RI	05/28/08	05/17/08
63438	GMAC Insurance (Wkrs)	Maryland Heights, MO	05/28/08	05/23/08
63439	Watson Laboratories, Inc. (State)	Carmel, NY	05/28/08	05/27/08
63440	Magline, Inc. (Wkrs)	Pinconning, MI	05/28/08	05/22/08
63441	Metaldyne Tubular Products (State)	Hamburg, MI	05/28/08	05/27/08
63442	Corinthian, Inc. (Wkrs)	Corinth, MS	05/29/08	05/28/08
63443	DME Company (Wkrs)	Lewiston, PA	05/29/08	05/28/08
63444	Skyline McMinnville Nomad Division (State)	McMinnville, OR	05/29/08	05/28/08
63445	Citation Corporation (Comp)	Grand Rapids, MI	05/29/08	05/28/08
63446	Comau, Inc./Plymouth Facility (Wkrs)	Plymouth, MI	05/30/08	05/29/08
63447	West Fraser, Inc. (State)	Leola, AR	05/30/08	05/29/08
63448	Prestolite Wire LLC (Comp)	Tifton, GA	05/30/08	05/29/08
63449	Lear Corporation (Comp)	Troy, MI	05/30/08	05/29/08
63450	Port of Port Angeles (Wkrs)	Port Angeles, WA	05/30/08	05/27/08
63451	Columbia Falls Aluminum Company LLC (Comp)	Columbia Falls, MT	05/30/08	05/29/08
63452	Katahdin Paper Company LLC (Comp)	Millinocket, ME	05/30/08	05/29/08

APPENDIX—Continued

[TAA petitions instituted between 5/27/08 and 5/30/08]

TA-W	Subject firm (petitioners)	Location	Date of institution	Date of petition
63453	Dell, Inc.—Topfer Manufacturing Center (State)	Round Rock, TX	05/30/08	05/29/08

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DEPARTMENT OF LABOR**Employment and Training Administration**

[TA–W–61,601]

Intel Corporation Fab 23 Colorado Springs, CO; Notice of Negative Determination on Remand

On March 24, 2008, the U.S. Court of International Trade (USCIT) granted the Department of Labor's request for voluntary remand to conduct further investigation in *Former Employees of Intel Corporation v. U.S. Secretary of Labor*, Court No. 07–00420.

On May 30, 2007, an official of Intel Corporation, Fab 23, Colorado Springs, Colorado (subject firm) filed a petition for Trade Adjustment Assistance (TAA) and Alternative Trade Adjustment Assistance (ATAA) on behalf of workers and former workers of the subject firm. The subject firm official stated that the subject firm produced “WiFi products” for Intel Corporation (Intel) and communication microprocessors for a company that replaced purchases from the subject firm with products manufactured by a Taiwanese company. The official further stated in the petition that “As a result of the production of these two product lines going overseas, Fab 23 no longer has product to build and will be ceasing production on August 4, 2007.” AR 2–3.

The institution of the TAA petition was published in the **Federal Register** on June 14, 2007 (72 FR 32915). AR 10–11.

In determining whether a petitioning worker group has met the statutory criteria, the Department refers to the applicable regulation, 29 CFR part 90, for guidance.

During the initial investigation, the subject firm official stated that the subject firm produced “silicon wafers” and that the worker separations were due to the subject firm's customer shifting to another company. AR 12. The company official also stated that the subject firm made silicon wafers for wireless fidelity (WiFi) chips and that the wafers were a component of the

WiFi cards imported into the United States. The company official further stated that the subject firm shifted silicon wafer production to Taiwan. AR 13. Further, information provided during the initial investigation confirmed that the subject firm produced silicon wafers bearing WiFi chips and communications microprocessors, that the subject workers were not separately identifiable by product line, and that the subject firm would close on August 4, 2007 due to the shift of production to Taiwan during the second and third quarters of 2007 (April–September 2007). AR 14.

The initial investigation further revealed that subject firm's production of silicon wafers increased in 2006 from 2005 levels and increased during January through April 2007 from January through April 2006 levels. AR 16.

The Department's Notice of negative determination, issued on June 15, 2007, regarding the subject workers' eligibility to apply for TAA/ATAA stated that sales and production for silicon wafers increased in 2005, 2006, and year to date 2007, that the subject firm did not import silicon wafers, and that the subject firm did not shift production of silicon wafers to a foreign country during the relevant period. AR 23–25. The determination published in the **Federal Register** on June 28, 2007 (72 FR 35517). AR 26–30.

In a letter dated July 14, 2007, a former worker, David Alexander, requested administrative reconsideration of the Department's negative determination. AR 39. The request for reconsideration alleged:

(1) That when Intel Corporation (Intel) sold the rights to the “Hermon” chip to another company, Intel became an agent of that principal company, and, subsequently, the subject workers became employees of the principal company;

(2) That the subject firm did not produce silicon wafers but “manufactures electronic circuits * * * on a silicon wafer”;

(3) That “(a) INTEL buys the bare silicon wafer from a supplier, (b) Fab 23 then manufactures the electronic circuit on the wafer called a die and (c) then die is tested and assembly. Item c can

be done else where, I believe at this time (July 2007) Marvel chooses elsewhere”;

(4) That the subject workers are secondary/downstream employees to the so-called principal company; and
(5) That the principal company's shift of production to Taiwan is a basis for TAA certification of the subject workers. AR 40–43.

In the request for reconsideration, Mr. Alexander stated that “packaged dies are called ‘chips.’” AR 41.

During the reconsideration investigation, the Department confirmed that a company, Marvel, purchased from Intel the rights to the Hermon chip, and that, under the agreement, the subject firm would produce silicon wafers bearing the Hermon chip until Marvel's Taiwanese supplier was fully operational. The subject firm ceased production in April 2007 and the last shipment of silicon wafers from the subject firm to Marvel was in the second quarter of 2007. AR 54–55. The Department also confirmed that the articles produced at the subject firm were silicon wafers bearing “WiFi semiconductor chips.” AR 57.

The subject firm also provided information about Intel's semiconductor chip production process.

The subject firm purchased bare silicon wafers from various vendors, AR 66, then used a photolithographic printing process to fabricate each chip onto the silicon wafer. AR 57, 65, 66. Each chip is called a die and is tested on the wafer before it was separated from the silicon wafer. AR 65, 74. The process of separating chips from the wafer is called “dicing” or “scribing.” AR 113.

The silicon wafers bearing WiFi semiconductor chips were sent from the subject firm to other Intel facilities. At these facilities, the wafers were diced and the semiconductor chips were packaged. AR 65–66, 101. The packaging of the chip entails “mounting the chip on a stamped lead-wire harness in a process called die bonding, then encapsulating this assembly in the final package.” AR 113.

Without this packaging process, the chip could not electrically communicate outside of itself, could not be placed into a motherboard, and had no customer application. AR 65–66. The dicing of silicon wafers and the